

# Dual J-K Flip-Flop with Reset

## MC74HC73A

The MC74HC73A is identical in pinout to the LS73. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

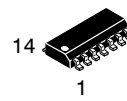
Each flip-flop is negative-edge clocked and has an active-low asynchronous reset.

The MC74HC73A is identical in function to the HC107, but has a different pinout.

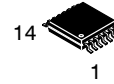
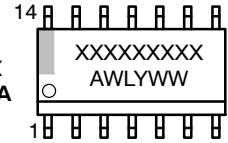
### Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0  $\mu$ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the JEDEC Standard No. 7.0 A Requirements
- Chip Complexity: 92 FETs or 23 Equivalent Gates
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

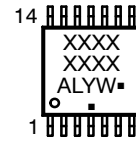
### MARKING DIAGRAMS



SOIC-14  
D SUFFIX  
CASE 751A



TSSOP-14  
DT SUFFIX  
CASE 948G



XXXX = Specific Device Code  
 A = Assembly Location  
 WL, L = Wafer Lot  
 Y = Year  
 WW, W = Work Week  
 G or  $\blacksquare$  = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.

# MC74HC73A

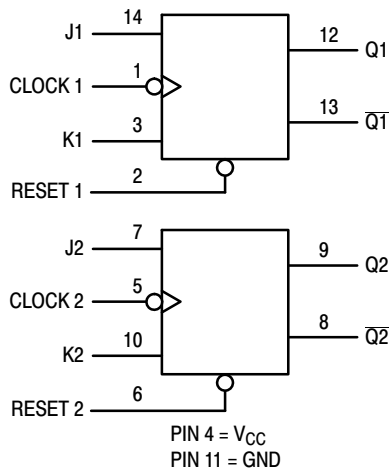


Figure 1. Logic Diagram

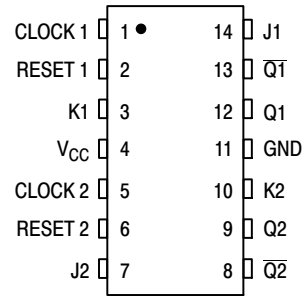


Figure 2. Pinout (Top View)

## FUNCTION TABLE

Inputs				Outputs	
Reset	Clock	J	K	Q	$\bar{Q}$
L	X	X	X	L	H
H	$\sim$	L	L	No Change	
H	$\sim$	L	H	L	H
H	$\sim$	H	L	H	L
H	$\sim$	H	H	Toggle	
H	L	X	X	No Change	
H	H	X	X	No Change	
H	$\surd$	X	X	No Change	

# MC74HC73A

## MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +6.5	V	
V <sub>IN</sub>	DC Input Voltage	-0.5 to V <sub>CC</sub> + 0.5	V	
V <sub>OUT</sub>	DC Output Voltage	-0.5 to V <sub>CC</sub> + 0.5	V	
I <sub>IN</sub>	DC Input Diode Current, per Pin	±20	mA	
I <sub>OUT</sub>	DC Output Diode Current, per Pin	±25	mA	
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA	
I <sub>IK</sub>	Input Clamp Current (V <sub>IN</sub> < 0 or V <sub>IN</sub> > V <sub>CC</sub> )	±20	mA	
I <sub>OK</sub>	Output Clamp Current (V <sub>OUT</sub> < 0 or V <sub>OUT</sub> > V <sub>CC</sub> )	±20	mA	
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C	
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C	
T <sub>J</sub>	Junction Temperature Under Bias	±150	°C	
θ <sub>JA</sub>	Thermal Resistance (Note 1)	SOIC-14 TSSOP-14	116 150	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 25°C	SOIC-14 TSSOP-14	1077 833	mW
MSL	Moisture Sensitivity		Level 1	-
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V <sub>ESD</sub>	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model	> 2000 N/A	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 76mm-by-114mm, 2-ounce copper trace no air flow per JESD51-7.
2. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Referenced to GND) (Note 3)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Free-Air Temperature	-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time			ns
	V <sub>CC</sub> = 2.0 V	0	1000	
	V <sub>CC</sub> = 4.5 V	0	500	
	V <sub>CC</sub> = 6.0 V	0	400	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

3. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

# MC74HC73A

## DC ELECTRICAL CHARACTERISTICS (MC74HC73A)

Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	Guaranteed Limit			Unit
				- 55 to 25°C	≤ 85°C	≤ 125°C	
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	2.0	1.5	1.5	1.5	V
			3.0	2.1	2.1	2.1	
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
V <sub>IL</sub>	Maximum Low-Level Input Voltage	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	2.0	0.3	0.3	0.3	V
			3.0	0.9	0.9	0.9	
			4.5	1.35	1.35	1.35	
			6.0	1.8	1.8	1.8	
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>				V	
		I <sub>OUT</sub>   ≤ 20 μA	2.0	1.9	1.9		1.9
			4.5	4.4	4.4		4.4
			6.0	5.9	5.9		5.9
		I <sub>OUT</sub>   ≤ 2.4 mA  I <sub>OUT</sub>   ≤ 4.0 mA  I <sub>OUT</sub>   ≤ 5.2 mA	3.0	2.48	2.34		2.2
			4.5	3.98	3.84		3.7
6.0	5.48		5.34	5.2			
V <sub>OL</sub>	Maximum Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>				V	
		I <sub>OUT</sub>   ≤ 20 μA	2.0	0.1	0.1		0.1
			4.5	0.1	0.1		0.1
			6.0	0.1	0.1		0.1
		I <sub>OUT</sub>   ≤ 2.4 mA  I <sub>OUT</sub>   ≤ 4.0 mA  I <sub>OUT</sub>   ≤ 5.2 mA	3.0	0.26	0.33		0.40
			4.5	0.26	0.33		0.40
6.0	0.26		0.33	0.40			
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	± 1.0	± 1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	V <sub>IN</sub> = V <sub>CC</sub> or GND I <sub>OUT</sub> = 0 μA	6.0	2.0	20	80	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# MC74HC73A

## AC ELECTRICAL CHARACTERISTICS (MC74HC73A)

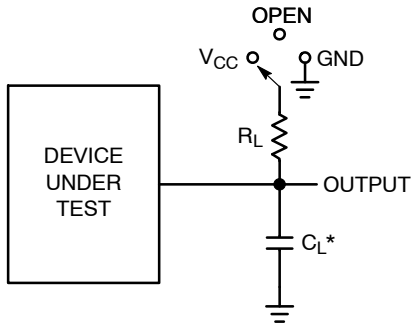
Symbol	Parameter	V <sub>CC</sub> V	Guaranteed Limit			Unit
			- 55 to 25°C	≤ 85°C	≤ 125°C	
f <sub>MAX</sub>	Maximum Clock Frequency (50% Duty Cycle) (Figure 4)	2.0	6.0	4.8	4.0	MHz
		3.0	15	10	8.0	
		4.5	30	24	20	
		6.0	35	28	24	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Clock to Q or $\bar{Q}$ (Figure 4)	2.0	125	155	190	ns
		3.0	TBD	TBD	TBD	
		4.5	25	31	38	
		6.0	21	26	32	
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Reset to Q or $\bar{Q}$ (Figure 5)	2.0	155	195	235	ns
		3.0	TBD	TBD	TBD	
		4.5	31	39	47	
		6.0	26	33	40	
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figure 4)	2.0	75	95	110	ns
		3.0	30	40	55	
		4.5	15	19	22	
		6.0	13	16	19	
C <sub>IN</sub>	Maximum Input Capacitance	—	10	10	10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Per Enabled Output) (Note 4)	5.0	Typical @ 25°C, V <sub>CC</sub> = 5.0 V			pF
			35			

4. Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

## TIMING REQUIREMENTS (MC74HC73A)

Symbol	Parameter	V <sub>CC</sub> V	Guaranteed Limit			Unit
			- 55 to 25°C	≤ 85°C	≤ 125°C	
t <sub>su</sub>	Minimum Setup Time, J or K to Clock (Figure 6)	2.0	100	125	150	ns
		3.0	TBD	TBD	TBD	
		4.5	20	25	30	
		6.0	17	21	26	
t <sub>h</sub>	Minimum Hold Time, Clock to J or K (Figure 6)	2.0	3.0	3.0	3.0	ns
		3.0	3.0	3.0	3.0	
		4.5	3.0	3.0	3.0	
		6.0	3.0	3.0	3.0	
t <sub>rec</sub>	Minimum Recovery Time, Reset Inactive to Clock (Figure 5)	2.0	100	125	150	ns
		3.0	TBD	TBD	TBD	
		4.5	20	25	30	
		6.0	17	21	26	
t <sub>w</sub>	Minimum Pulse Width, Clock (Figure 4)	2.0	80	100	120	ns
		3.0	TBD	TBD	TBD	
		4.5	16	20	24	
		6.0	14	17	20	
t <sub>w</sub>	Minimum Pulse Width, Reset (Figure 5)	2.0	80	100	120	ns
		3.0	TBD	TBD	TBD	
		4.5	16	20	24	
		6.0	14	17	20	
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times (Figure 4)	2.0	1000	1000	1000	ns
		3.0	800	800	800	
		4.5	500	500	500	
		6.0	400	400	400	

# MC74HC73A



\* $C_L$  Includes probe and jig capacitance

Test	Switch Position	$C_L$	$R_L$
$t_{PLH} / t_{PHL}$	Open	50 pF	1 k $\Omega$
$t_{PLZ} / t_{PZL}$	$V_{CC}$		
$t_{PHZ} / t_{PZH}$	GND		

Figure 3. Test Circuit

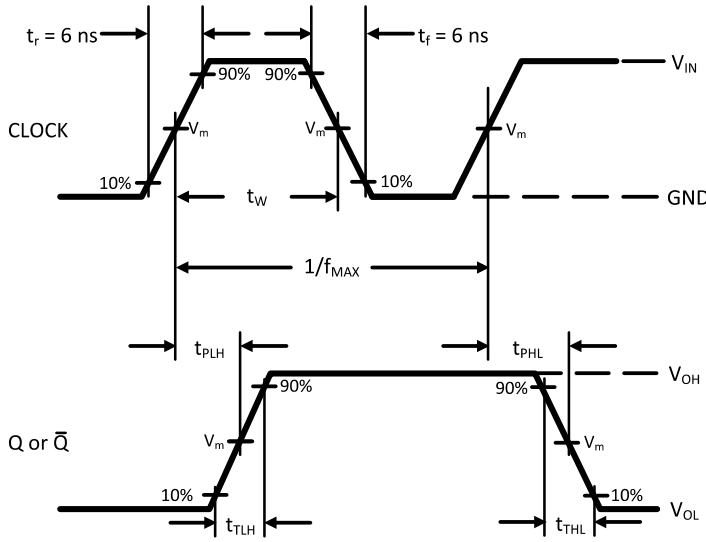


Figure 4.

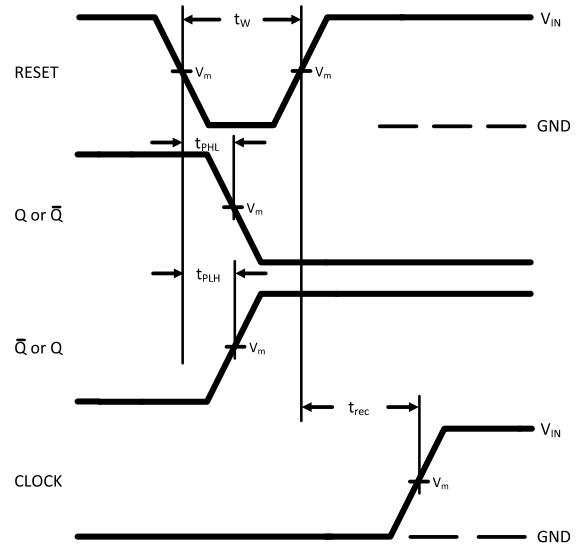


Figure 5.

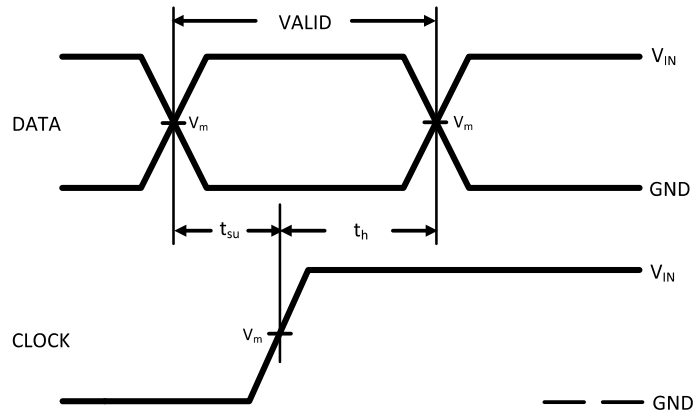


Figure 6.

Device	$V_{IN}, V$	$V_m, V$
MC74HC73A	$V_{CC}$	50% x $V_{CC}$

# MC74HC73A

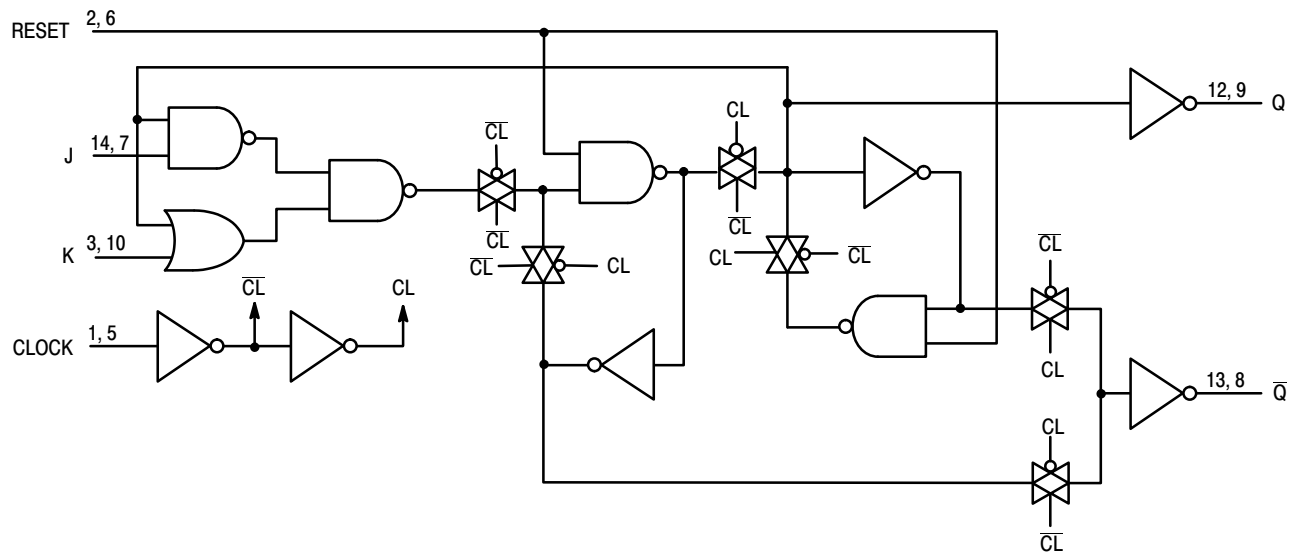


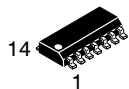
Figure 7. Expanded Logic Diagram

## ORDERING INFORMATION

Device	Marking	Package	Shipping <sup>†</sup>
MC74HC73ADG	HC73AG	SOIC-14	55 Units / Rail
MC74HC73ADR2G	HC73AG	SOIC-14	2500 / Tape & Reel
MC74HC73ADR2G-Q*	HC73AG	SOIC-14	2500 / Tape & Reel
MC74HC73ADTR2G	HC 73A	TSSOP-14	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

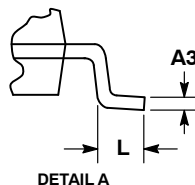
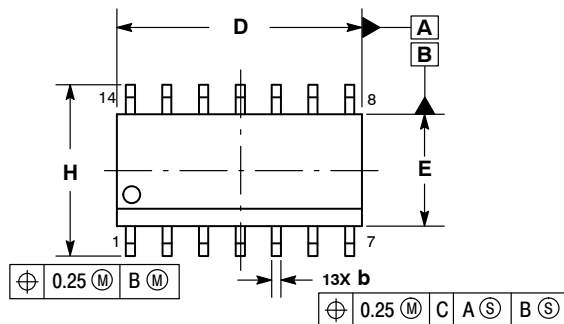
\*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.



SCALE 1:1

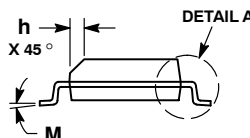
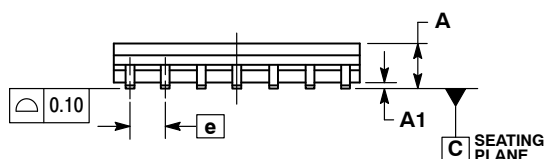
SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

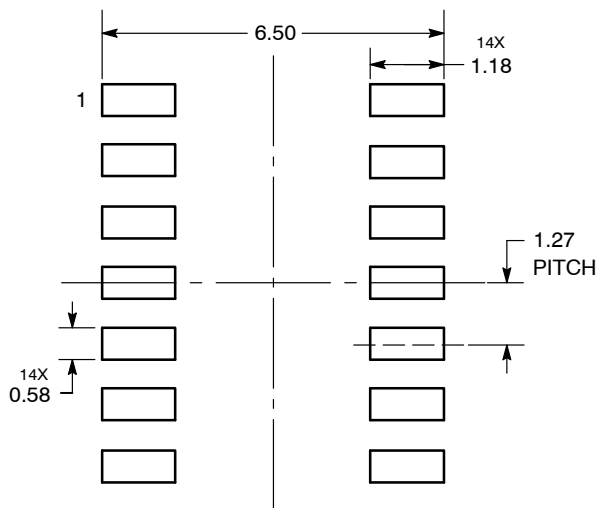


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
  5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°



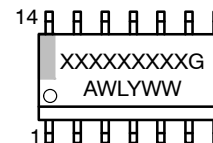
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM\*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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**SOIC-14**  
**CASE 751A-03**  
**ISSUE L**

DATE 03 FEB 2016

STYLE 1:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. NO CONNECTION  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 2:  
 CANCELLED

STYLE 3:  
 PIN 1. NO CONNECTION  
 2. ANODE  
 3. ANODE  
 4. NO CONNECTION  
 5. ANODE  
 6. NO CONNECTION  
 7. ANODE  
 8. ANODE  
 9. ANODE  
 10. NO CONNECTION  
 11. ANODE  
 12. ANODE  
 13. NO CONNECTION  
 14. COMMON CATHODE

STYLE 4:  
 PIN 1. NO CONNECTION  
 2. CATHODE  
 3. CATHODE  
 4. NO CONNECTION  
 5. CATHODE  
 6. NO CONNECTION  
 7. CATHODE  
 8. CATHODE  
 9. CATHODE  
 10. NO CONNECTION  
 11. CATHODE  
 12. CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 5:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. NO CONNECTION  
 7. COMMON ANODE  
 8. COMMON CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. ANODE/CATHODE  
 12. ANODE/CATHODE  
 13. NO CONNECTION  
 14. COMMON ANODE

STYLE 6:  
 PIN 1. CATHODE  
 2. CATHODE  
 3. CATHODE  
 4. CATHODE  
 5. CATHODE  
 6. CATHODE  
 7. CATHODE  
 8. ANODE  
 9. ANODE  
 10. ANODE  
 11. ANODE  
 12. ANODE  
 13. ANODE  
 14. ANODE

STYLE 7:  
 PIN 1. ANODE/CATHODE  
 2. COMMON ANODE  
 3. COMMON CATHODE  
 4. ANODE/CATHODE  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. ANODE/CATHODE  
 8. ANODE/CATHODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. COMMON CATHODE  
 12. COMMON ANODE  
 13. ANODE/CATHODE  
 14. ANODE/CATHODE

STYLE 8:  
 PIN 1. COMMON CATHODE  
 2. ANODE/CATHODE  
 3. ANODE/CATHODE  
 4. NO CONNECTION  
 5. ANODE/CATHODE  
 6. ANODE/CATHODE  
 7. COMMON ANODE  
 8. COMMON ANODE  
 9. ANODE/CATHODE  
 10. ANODE/CATHODE  
 11. NO CONNECTION  
 12. ANODE/CATHODE  
 13. ANODE/CATHODE  
 14. COMMON CATHODE

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<b>DESCRIPTION:</b>	<b>SOIC-14 NB</b>	<b>PAGE 2 OF 2</b>

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# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



**TSSOP-14 WB**  
CASE 948G  
ISSUE C

DATE 17 FEB 2016

SCALE 2:1



**NOTES:**

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**GENERIC MARKING DIAGRAM\***

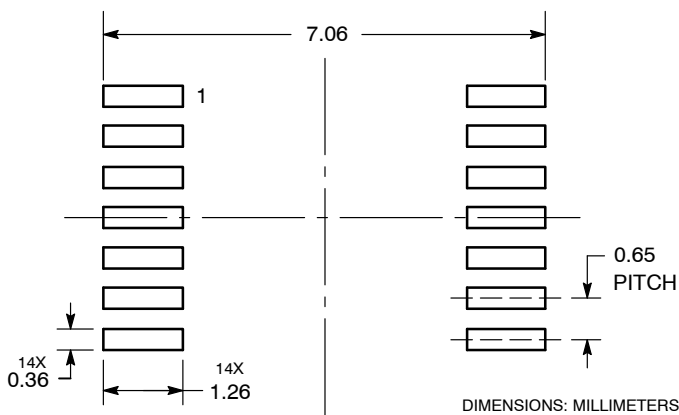


- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

**SOLDERING FOOTPRINT**



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